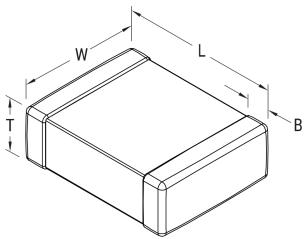


CBR04C200J5GAC

CBR-SMD RF COG, Ceramic, 20 pF, 5%, 50 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0402



Click here for the 3D model.

Dimensions	
Chip Size	0402
L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
T	0.5mm +/-0.05mm
В	0.25mm +0.05/-0.1mm

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	10000

Series CBR-SMD RF COG Style SMD Chip Description SMD, Fixed, RF, Ultra High Q, Low ESR, Class I Features Ultra High Q, Low ESR, Class I RoHS Yes Termination Tin Marking No AEC-Q200 No
Description SMD, Fixed, RF, Ultra High Q, Low ESR, Class I Features Ultra High Q, Low ESR, Class I RoHS Yes Termination Tin Marking No AEC-Q200 No
Description Class I Features Ultra High Q, Low ESR, Class I RoHS Yes Termination Tin Marking No AEC-Q200 No
RoHS Yes Termination Tin Marking No AEC-Q200 No
Termination Tin Marking No AEC-Q200 No
Marking No AEC-Q200 No
AEC-Q200 No
Typical Component
Typical Component 1.37 mg Weight
Notes Solder Reflow Only.
Shelf Life 78 Weeks
MSL 1

Specifications	
Capacitance	20 pF
Capacitance Tolerance	5%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Dissipation Factor	0.125%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	800

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